

SOT750A

leadless surface mounted package; plastic cap; 28 terminations

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QMAN28
Package type industry code	QMAN28
Package style descriptive code	QMAN (quad microelectronic assembly; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.35	-	10.5	10.65	mm
E	package width	8.35	-	8.5	8.65	mm
A	seated height	1.7	-	1.8	1.9	mm
n ₂	actual quantity of termination	-	-	28	-	



2. Package outline

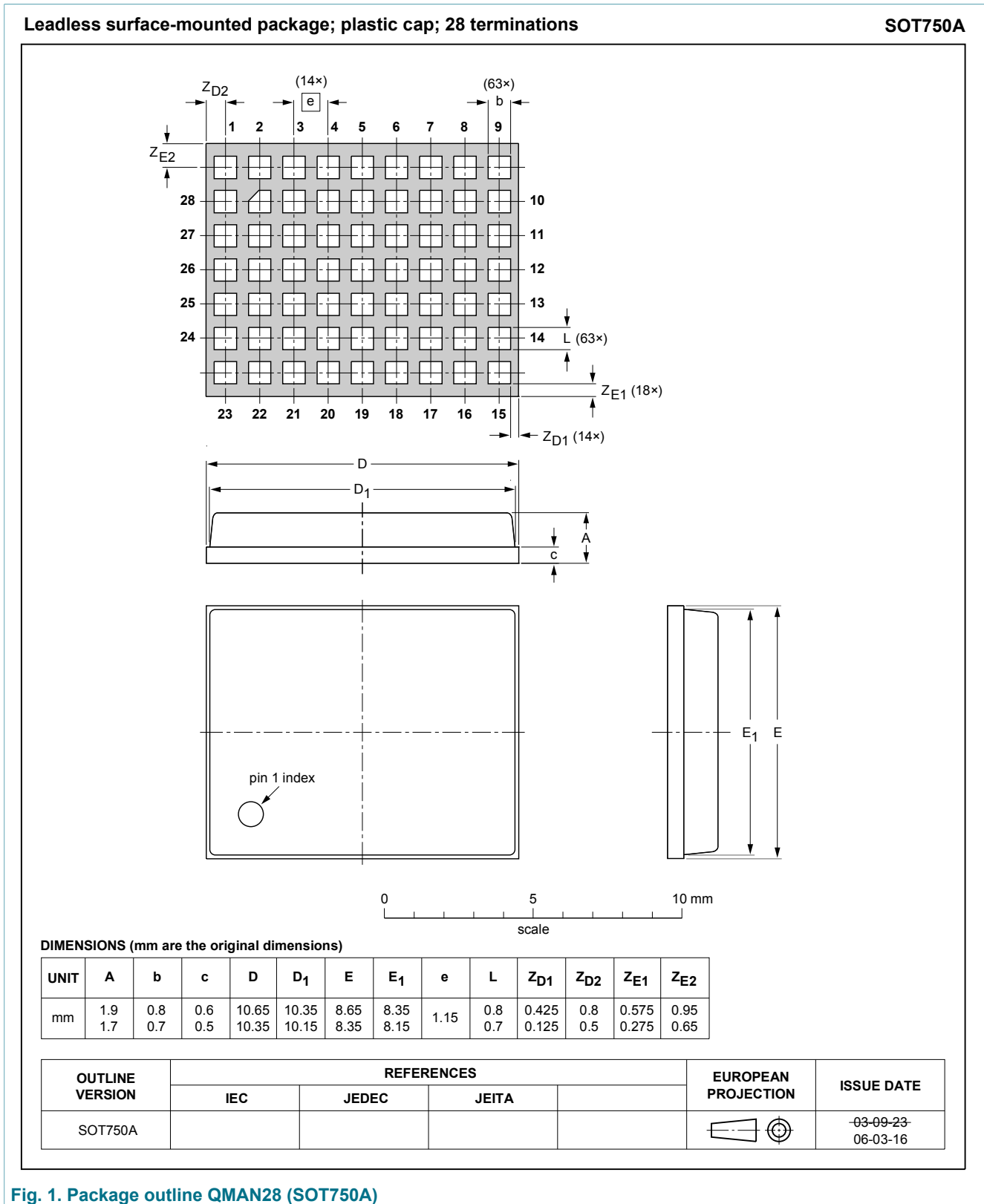


Fig. 1. Package outline QMAN28 (SOT750A)

3. Legal information

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